

Thick Film Metallization: Ag - Polymer

substrate material	ANCeram Aluminium Nitride (AlN)
surface	Standard, CLA < 1.0 µm
metallization	Ag polymer paste
film thickness	25 µm (typ.)
sheet resistivity	60 ± 10 mΩ/□
dimensions	according to customers' specification
min. line width	200 µm
min. line spacing	200 µm
recommended solder	PbSn (limited)
adhesive strength	> 5 N/mm ²

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